



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Yamauchi, M.

Serial No.: 09/733,036

Group Art Unit: 2828

Filed: December 11, 2000

Examiner: Leung, Q.

For: SEMICONDUCTOR LASER DIODE CHIP AND ITS POSITIONING AND MOUNTING METHOD

Honorable Assistant Commissioner of Patents
Washington, D.C. 20231
BOX AF

AMENDMENT UNDER 37 C.F.R. §1.116

Sir:

In response to the Office Action dated July 2, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 4 and 24 without prejudice or disclaimer.

Please amend the claims as follows.

1. (Amended) A semiconductor laser diode chip comprising:
a first mark formed at a predetermined position with respect to an active layer on a face opposed to a substrate to which the chip is mounted; and
a second mark that satisfies a predetermined relative position relation to said first mark and is positioned oppositely to a substrate side mark formed on said substrate at mounting time to said substrate,
wherein said first mark is constructed by a thin line formed on an upper portion of said active layer.

21. (Amended) A semiconductor laser diode chip with an active layer mounted on a substrate, comprising:
a first pair of marks formed in the vicinity of said active layer and straddling said

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